SDLS139 - APRIL 1985 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

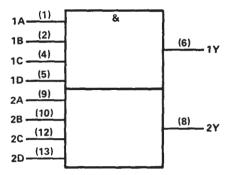
These devices contain two independent 4-input AND gates.

The SN54LS21 is characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN74LS21 is characterized for operation from 0 °C to 70 °C.

FUNCTION	TABLE	(each	gate)
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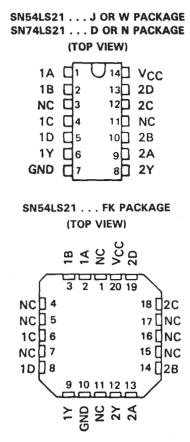
	INP	UTS		OUTPUT
A	в	С	D	Y
н	н	н	н	н
L	x	х	x	L
X	L	х	X	L
X	х	L	X	L
X	х	х	L	L

logic symbol[†]



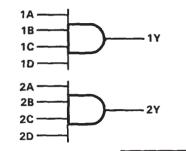
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.



NC-No internal connection

logic diagram



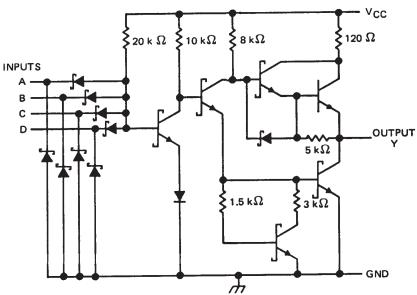
(positive logic) Y = A•B•C•D or Y = $\overline{\overline{A} + \overline{B} + \overline{C} + \overline{D}}$

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

SN54LS21, SN74LS21 DUAL 4-INPUT POSITIVE-AND GATES

SDLS139 – APRIL 1985 – REVISED MARCH 1988

schematics (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	
Operating free-air temperature range: SN54'	-55°C to 125°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminals.



SN54LS21, SN74LS21 DUAL 4-INPUT POSITIVE-AND GATES

SDLS139 - APRIL 1985 - REVISED MARCH 1988

recommended operating conditions

		SN54LS21			SN74LS21			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	v	
VIH High-level input voltage	2			2			V	
VIL Low-level input voltage			0.7			0.8	V	
OH High-level output current			- 0.4			- 0.4	mA	
IOL Low-level output current			4			8	mA	
T _A Operating free-air temperature	- 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS T			SN54LS	521				
PARAMETER					TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	l _l = – 18 mA				- 1.5			1.5	V
VOH	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OH} ≂ – 0.4 mA	2.5	3.4		2.7	3.4		v
	V _{CC} = MIN,	VIL = MAX,	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	v
VOL VCC =	V _{CC} = MIN,	VIL = MAX,	I _{OL} = 8 mA					0.35	0.5	
1	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
Чн	V _{CC} = MAX,	V _I = 2.7 V				20			20	μA
	V _{CC} = MAX,	V _I = 0.4 V				- 0.4			- 0.4	mA
los§	V _{CC} = MAX			- 20		- 100	- 20		- 100	mA
Іссн	V _{CC} = MAX,	V ₁ = 4.5 V			1.2	2.4		1.2	2.4	mA
ICCL	V _{CC} = MAX,	V _I = 0 V			2.2	4.4		2.2	4.4	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 \ddagger All typical values are at V_{CC} = 5 V, T_A = 25^oC § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COND	MIN	TYP	MAX	UNIT	
tPLH		~	B 2 kg	C. = 15 oF		8	15	ns
tPHL	Алу	Ť	$R_{L} = 2 k\Omega,$	CL = 15 pF		10	20	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/31003B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003B2A	Samples
JM38510/31003BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003BCA	Samples
JM38510/31003BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003BDA	Samples
M38510/31003B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003B2A	Samples
M38510/31003BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003BCA	Samples
M38510/31003BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003BDA	Samples
SN54LS21J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS21J	Samples
SN74LS21D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS21	Samples
SN74LS21DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS21	Samples
SN74LS21N	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS21N	Samples
SN74LS21NE4	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS21N	Samples
SN74LS21NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS21	Samples
SNJ54LS21FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 21FK	Samples
SNJ54LS21J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS21J	Samples
SNJ54LS21W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS21W	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.



OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS21, SN74LS21 :

Catalog : SN74LS21

• Military : SN54LS21

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

Texas Instruments

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All	dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74LS21DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74LS21NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



www.ti.com

PACKAGE MATERIALS INFORMATION

5-Jan-2022



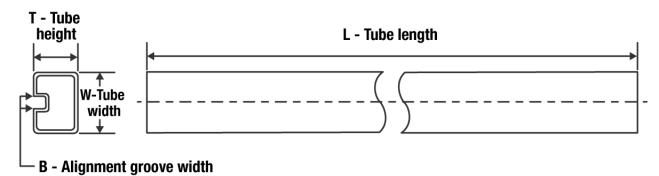
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS21DR	SOIC	D	14	2500	853.0	449.0	35.0
SN74LS21NSR	SO	NS	14	2000	853.0	449.0	35.0



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TUBE



*All dimensions are nominal								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/31003B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/31003B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74LS21D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS21N	Ν	PDIP	14	25	506	13.97	11230	4.32
SN74LS21N	Ν	PDIP	14	25	506	13.97	11230	4.32
SN74LS21NE4	Ν	PDIP	14	25	506	13.97	11230	4.32
SN74LS21NE4	Ν	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS21FK	FK	LCCC	20	1	506.98	12.06	2030	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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